

(2.00 mm) .0787"

FLEXIBLE ELEVATED SOCKET STRIPS

SPECIFICATIONS

For complete specifications see www.samtec.com?ESQT

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Sn or Au over

50 μ " (1.27 μ m) Ni

Current Rating (ESQT/TMMH):

4.5 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(2.62 mm) .103" to

(5.03 mm) .198" with

(0.38 mm) .015" wipe

Max Cycles:

100 with 10 μ " (0.25 μ m) Au

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes, for -S, -D & -Q

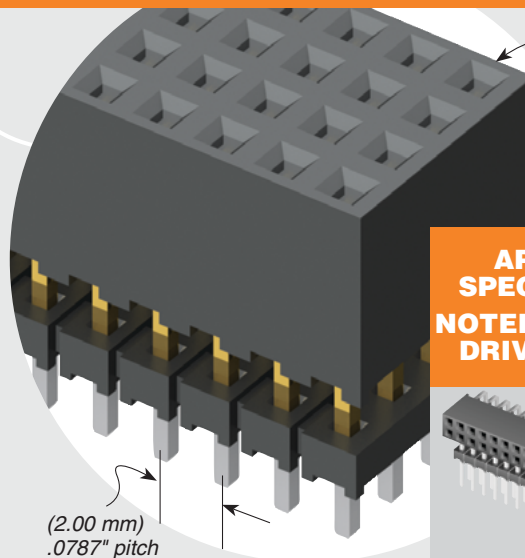
(Wave only for -T, -5 & -6)

Board Mates:

TMMH, TMM, MTMM,
MMT, TW, LTMM, ZLTMM,
ESQT, PTT, TSH, TMMS

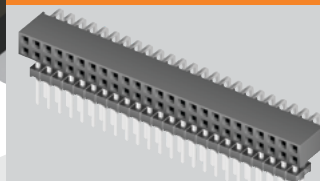
Cable Mates:

TCMD



High-retention
contacts

APPLICATION SPECIFIC OPTION: NOTEBOOK 2.5" DISK DRIVE INTERFACE



Call for part number.

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

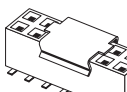


Note:
This Series is non-standard,
non-returnable.

Other Solutions

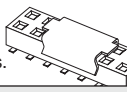
Surface Mount

See SQW and TLE Series.



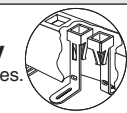
Low Profile

See CLT Series.



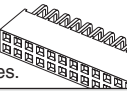
High Reliability

See SMM Series.



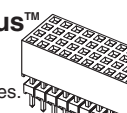
Right-Angle

See SQW Series.



PC/104-Plus™ Sockets

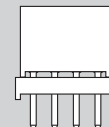
See ESQT-368 and PTHF Series.



ESQT	1	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	ROW OPTION	BODY HEIGHT	OTHER OPTION
02 thru 50			Specify LEAD STYLE from chart	-F = Gold flash on contact, Matte Tin on tail -L = 10 μ " (0.25 μ m) Gold on contact, Matte Tin on tail -M = 20 μ " (0.51 μ m) Gold on contact, Matte Tin on tail -GF = 15 μ " (0.38 μ m) Gold on contact, Gold flash on tail (Recommended for self-nesting) (-02 lead style only)	-S = Single Row -D = Double Row -T = Triple Row -Q = Quad Row -5 = Five Row -6 = Six Row	"XXX" = Body Height (in inches) (7.87 mm) .310" minimum for -S, -D, -Q (9.53 mm) .375" minimum for -T, -5, -6	"XXX" = Polarized Position (Indicate position number)

LEAD STYLE	A	MAX TAIL	MAX BODY HEIGHT
-02	(21.59) .850	(13.72) .540	(20.32) .800
-03	(11.63) .458	(3.76) .148	(10.36) .408

OTHER SOLUTIONS



Paste In Hole (PIH) processing.
Contact Samtec ASP Group.
(Not recommended for stack through applications)

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.